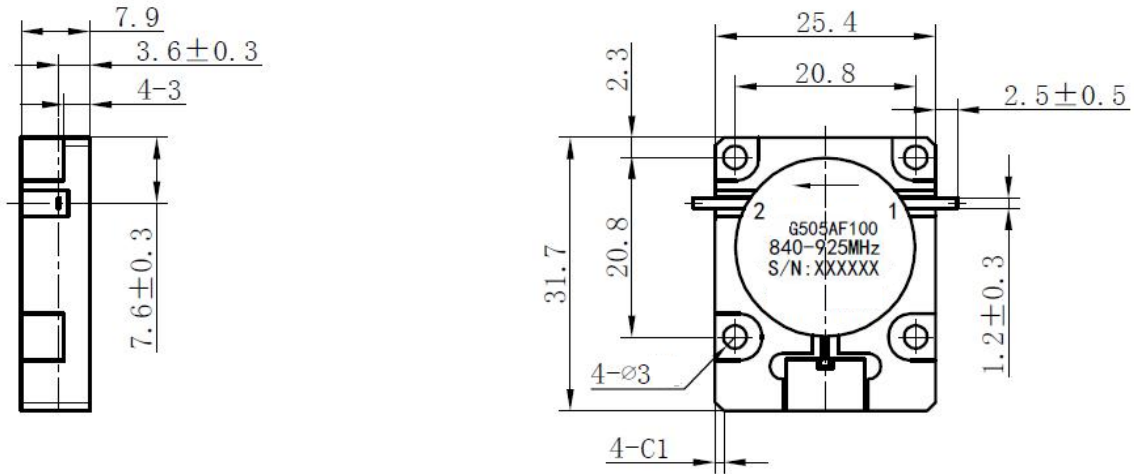


1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

2.Dimensions



3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G505A[840-925]MHz	0.840	0.925	0.883	0.085	23	0.3	1.15	150	
G505A[869-894]MHz	0.869	0.894	0.882	0.025	23	0.325	1.15	150	-65
G505A[925-960]MHz	0.925	0.960	0.943	0.035	25	0.25	1.15	100	
G505A[1800-1950]MHz	1.800	1.950	1.8750	0.150	22	0.3	1.17	150	
G505A[1805-1880]MHz	1.805	1.880	1.8375	0.075	25	0.25	1.15	150	
G505A[1920-1980]MHz	1.920	1.980	1.9500	0.060	25	0.2	1.15	100	
G505A[1930-1990]MHz	1.930	1.990	1.9600	0.060	25	0.2	1.15	100	
G505A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.15	100	